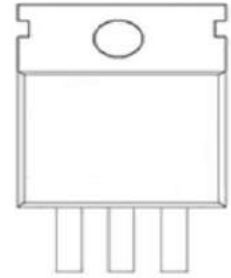
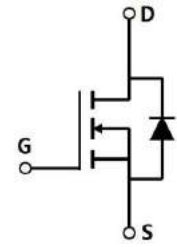


## 80V N-Channel Enhancement Mode MOSFET

### General Description

70N08 use advanced Trench MOSFET technology to provide low RDS(ON), low gate charge, fast switching. This device is specially designed to get better ruggedness and suitable to use in

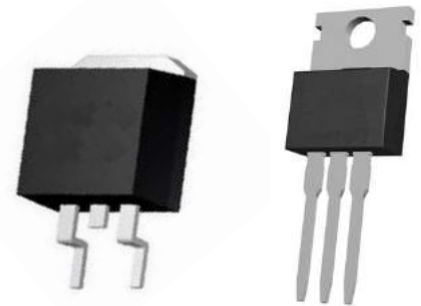


### Features

- Low RDS(on) & FOM
- Extremely low switching loss
- Excellent stability and uniformity of Invertors

### Applications

- Consumer electronic power supply Motor control
- Synchronous-rectification Isolated DC
- Synchronous-rectification applications



### Absolute Maximum Ratings at $T_j=25^{\circ}\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage ( $V_{GS}=0V$ )	$V_{DS}$	80	V
Gate-Source Voltage ( $V_{DS}=0V$ )	$V_{GS}$	$\pm 20$	V
Drain Current (DC) at $T_c=25^{\circ}\text{C}$	$I_D$ (DC)	78	A
Drain Current (DC) at $T_c=100^{\circ}\text{C}$	$I_D$ (DC)	55	A
Drain Current-Continuous@ Current-Pulsed <small>(Note 1)</small>	$I_{DM}$ (pluse)	300	A
Peak diode recovery voltage	$dv/dt$	30	V/ns
Maximum Power Dissipation( $T_c=25^{\circ}\text{C}$ )	$P_D$	160	W
Derating factor		1.07	W/ $^{\circ}\text{C}$
Single pulse avalanche energy <small>(Note 2)</small>	$E_{AS}$	550	mJ
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 175	$^{\circ}\text{C}$
Thermal Resistance, Junction-to-Case (Maximum)	$R_{thJC}$	0.94	$^{\circ}\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient (Maximum)	$R_{thJA}$	63	$^{\circ}\text{C}/\text{W}$

**80V N-Channel Enhancement Mode MOSFET**
**Electrical Characteristics** at  $T_j=25\text{ }^\circ\text{C}$  unless otherwise specified

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	80		-	V
Zero Gate Voltage Drain Current( $T_c=25\text{ }^\circ\text{C}$ )	$I_{DSS}$	$V_{DS}=75V, V_{GS}=0V$	-	-	1	$\mu A$
Zero Gate Voltage Drain Current( $T_c=125\text{ }^\circ\text{C}$ )	$I_{DSS}$	$V_{DS}=75V, V_{GS}=0V$	-	-	10	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	2		4	V
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=40A$	-	8.5	10	m $\Omega$
Forward Transconductance	$g_{FS}$	$V_{DS}=5V, I_D=30A$	-	60	-	S
Input Capacitance	$C_{iss}$	$V_{DS}=25V, V_{GS}=0V,$ $F=1.0MHz$	-	3400	-	PF
Output Capacitance	$C_{oss}$		-	290	-	PF
Reverse Transfer Capacitance	$C_{rss}$		-	221	-	PF
Total Gate Charge	$Q_g$	$V_{DS}=30V, I_D=30A,$ $V_{GS}=10V$	-	94	-	nC
Gate-Source Charge	$Q_{gs}$		-	16	-	nC
Gate-Drain Charge	$Q_{gd}$		-	24	-	nC
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=30V, I_D=2A, R_L=15\Omega$ $V_{GS}=10V, R_G=2.5\Omega$	-	15	-	nS
Turn-on Rise Time	$t_r$		-	11	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	52	-	nS
Turn-Off Fall Time	$t_f$		-	13	-	nS
Source-drain current(Body Diode)	$I_{SD}$		-	-	78	A
Pulsed Source-drain current(Body Diode)	$I_{SDM}$		-	-	312	A
(Note 1) Forward on voltage	$V_{SD}$	$T_j=25\text{ }^\circ\text{C}, I_{SD}=40A, V_{GS}=0V$	-	-	1.2	V
(Note 1) Reverse Recovery Time	$t_{rr}$	$T_j=25\text{ }^\circ\text{C}, I_F=75A, di/dt=100A/\mu s$	-	-	33	nS
(Note 1) Reverse Recovery Charge	$Q_{rr}$		-	-	54	nC
Forward Turn-on Time	$t_{on}$	Intrinsic turn-on time is negligible(turn-on is dominated by $L_S+L_D$ )				

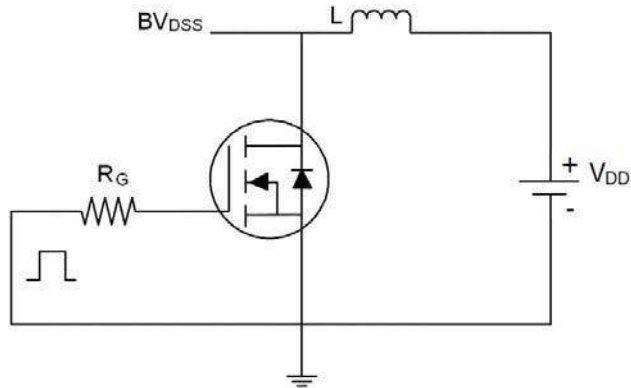
**Note**

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3)  $P_d$  is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with  $T_a=25\text{ }^\circ\text{C}$ .

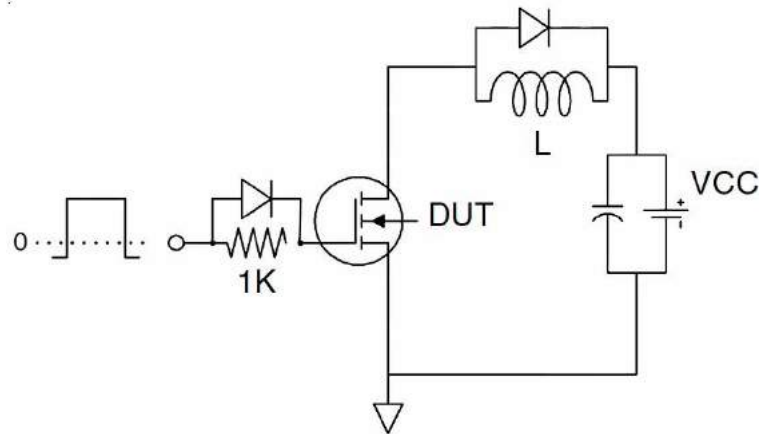
80V N-Channel Enhancement Mode MOSFET

Test Circuit

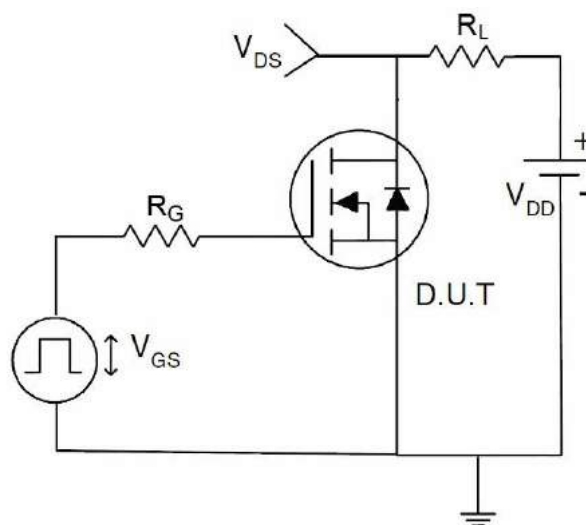
1)  $E_{AS}$  test circuit



2) Gate charge test circuit



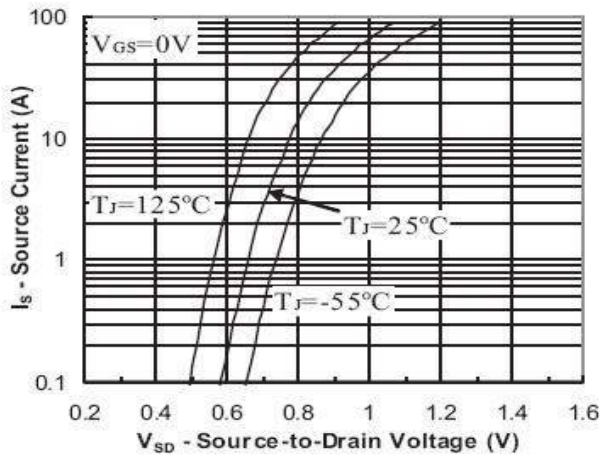
3) Switch Time Test Circuit



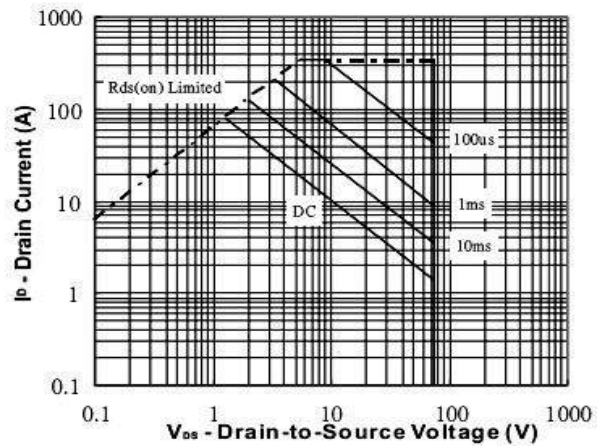
**80V N-Channel Enhancement Mode MOSFET**

**Typical Electrical and Thermal Characteristics (curves)**

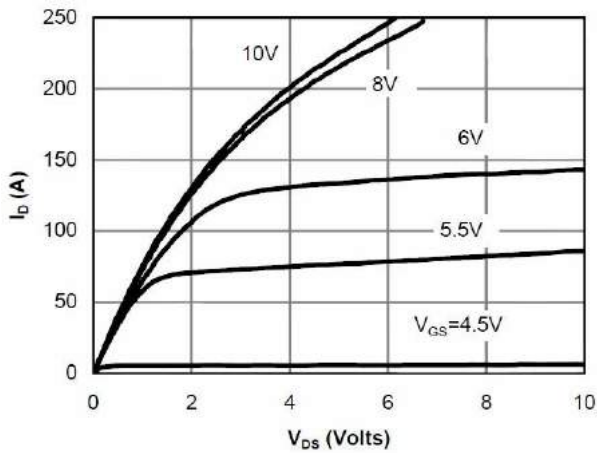
**Figure1. Safe operating area**



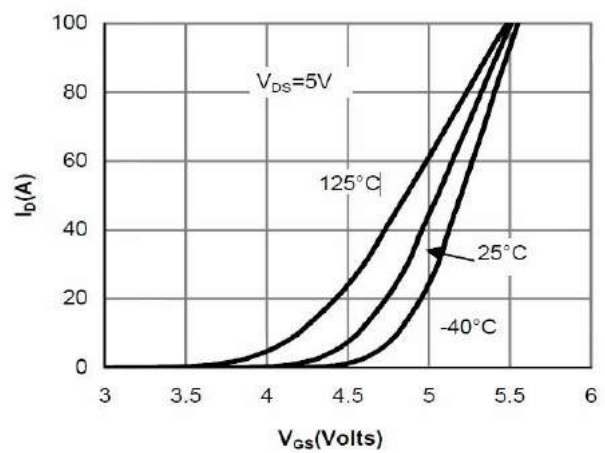
**Figure2. Source-Drain Diode Forward Voltage**



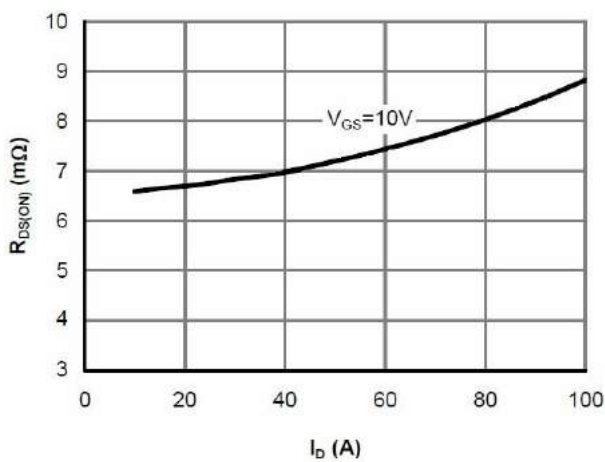
**Figure3. Output characteristics**



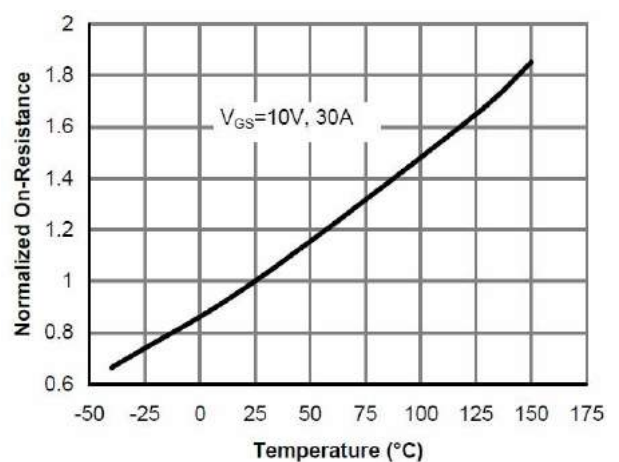
**Figure4. Transfer characteristics**



**Figure5. Static drain-source on resistance**



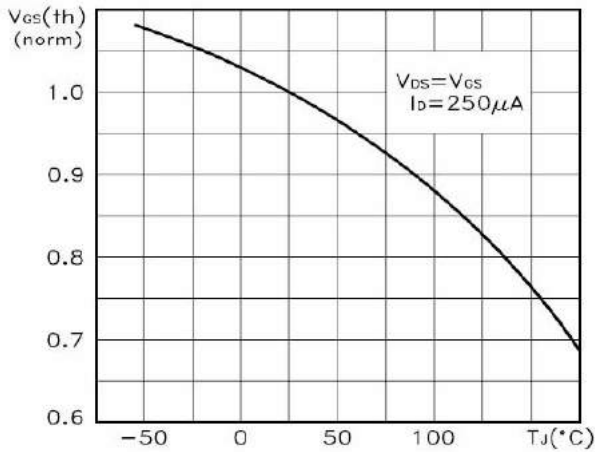
**Figure6. RDS(ON) vs Junction Temperature**



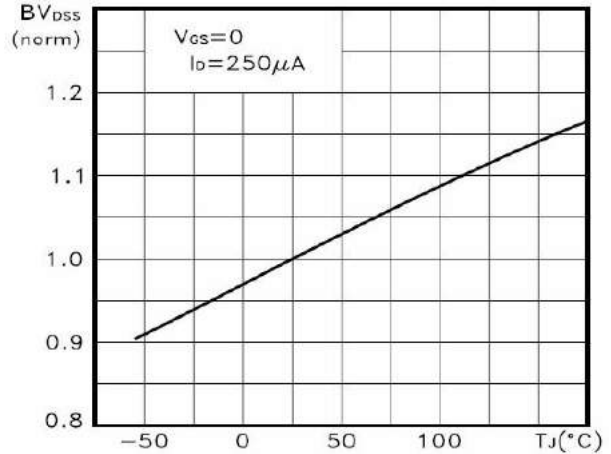
**Figure7. BVDS vs Junction Temperature**

**Figure8. VGS(th) vs Junction Temperature**

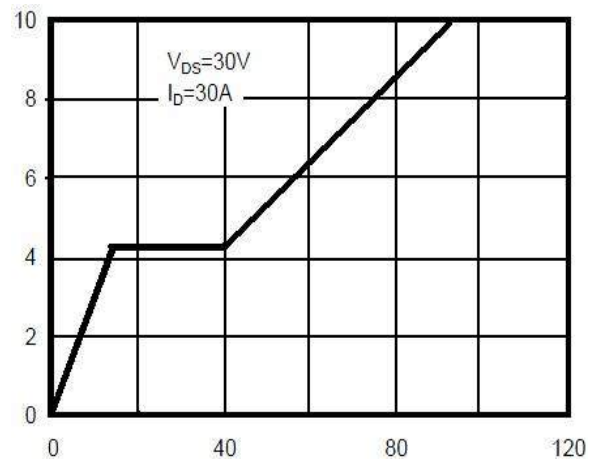
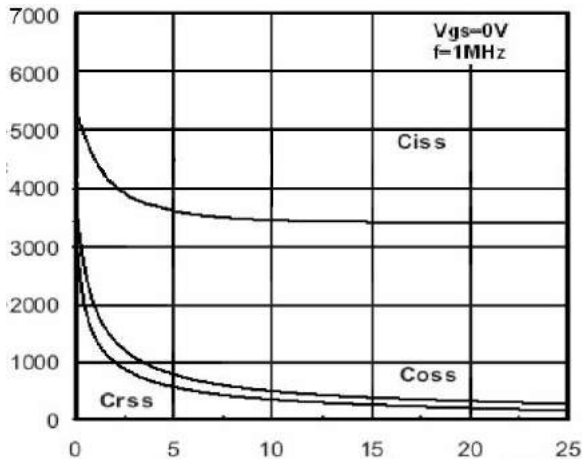
**80V N-Channel Enhancement Mode MOSFET**



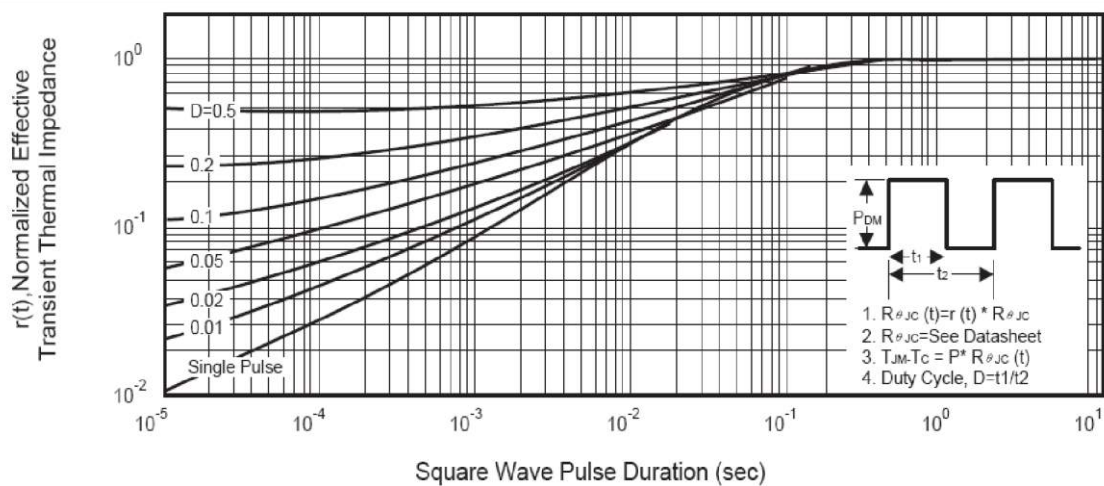
**Figure9. Capacitance**



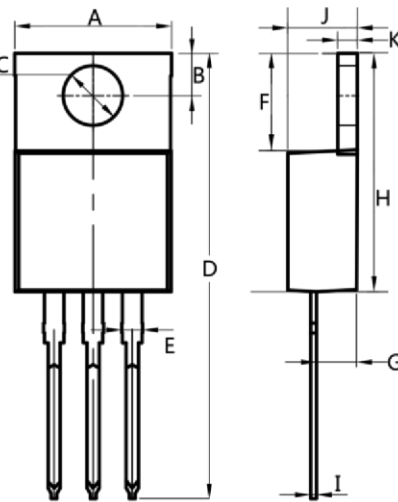
**Figure10. Gate charge waveforms**



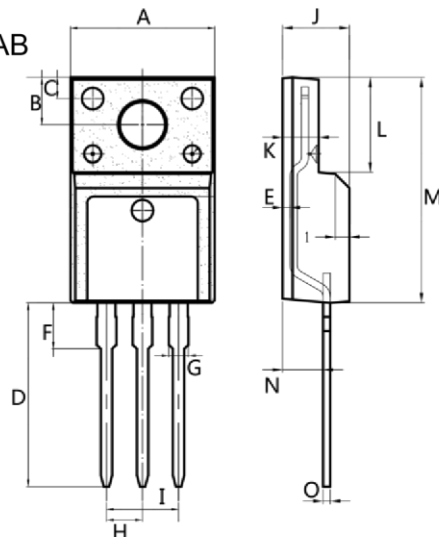
**Figure11. Normalized Maximum Transient Thermal Impedance**



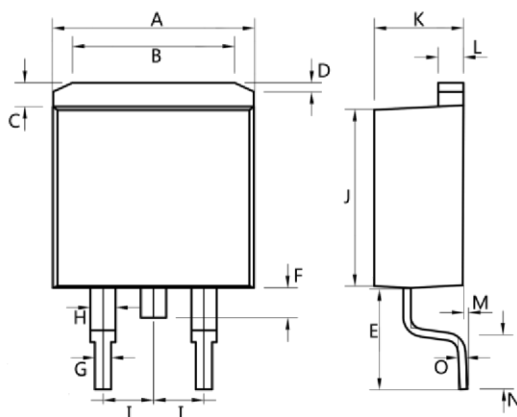
## 80V N-Channel Enhancement Mode MOSFET

**TO-220AB**


Dim.	Min.	Max.
A	10.0	10.4
B	2.5	3.0
C	3.5	4.0
D	28.0	30.0
E	1.1	1.5
F	6.2	6.6
G	2.9	3.3
H	15.0	16.0
I	0.35	0.45
J	4.3	4.7
K	1.2	1.4
All Dimensions in millimeter		

**ITO-220AB**


Dim.	Min.	Max.
A	9.9	10.3
B	2.9	3.5
C	1.15	1.45
D	12.75	13.25
E	0.55	0.75
F	3.1	3.5
G	1.25	1.45
H	Typ 2.54	
I	Typ 5.08	
J	4.55	4.75
K	2.4	2.7
L	6.35	6.75
M	15.0	16.0
N	2.75	3.15
O	0.45	0.60
All Dimensions in millimeter		

**TO-263**


Dim.	Min.	Max.
A	10.0	10.5
B	7.25	7.75
C	1.3	1.5
D	0.55	0.75
E	5.0	6.0
F	1.4	1.6
G	0.75	0.95
H	1.15	1.35
I	Typ 2.54	
J	8.4	8.6
K	4.4	4.6
L	1.25	1.45
M	0.02	0.1
N	2.4	2.8
O	0.35	0.45
All Dimensions in millimeter		